Applicant: William James Palmteer and Philip Joseph Beucler	
Application No: 09/966,222	Art Group: 2827
Filing Date: 09/28/2001	Examiner: Lourdes C. Cruz
Attorney Docket No: 17658 (S&L No. 24,989A USA)	
Title: IMPROVED LEADFRAME-BASED CHIP SCALE PACKAGE	
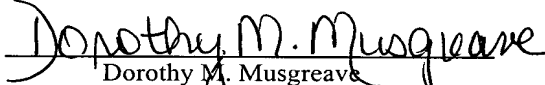
Mail Stop Non-Fee Amendment
Commissioner for Patents
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to Mail Stop Non-Fee Amendment,Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on Friday, May 23, 2003.

Dorothy M. Musgreave

REPLY UNDER 37 CFR §1.111 TO OFFICE COMMUNICATION MAILED APRIL 23, 2003

This reply is being filed in response to the Office Communication mailed April 23, 2003 in connection with the above captioned application.
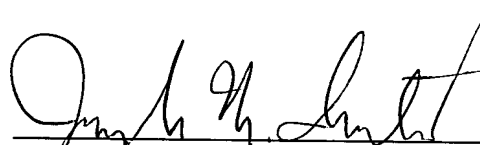
REMARKS

Drawings

Corrected drawings are attached as Exhibit A to this reply. Figures 2A, 2B, 2C, 2D, and 3 have been edited to correct the cross hatching pattern shown in the metal areas of the chip scale package. Figure 1B showing the prior art is correctly cross-hatched in accordance with MPEP §608.02.

These drawings were previously submitted with the response to the Office Action of September 23, 2002 (filed with the U.S. Patent Office on December 23, 2003). It appears, however, that these drawings were misplaced and thus Applicant is re-submitting them. The Examiner is invited to contact Applicant's undersigned counsel by telephone call with any questions or concerns regarding these drawings, or in order to further the prosecution of this case in any way.

Respectfully submitted,

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EXHIBIT A